

# Applying a Drain Voltage to an NMOS Device

Say we apply a voltage at the **gate** of an NMOS device that is sufficiently large to **induce** a conducting channel (i.e.,  $V_{GS} - V_t > 0$ ).

Now, say that we additionally place a voltage at the NMOS **drain electrode**, such that:

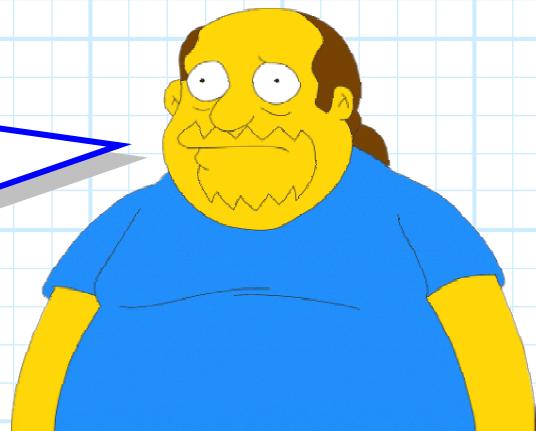
$$V_{DS} > 0$$

where:

$$V_{DS} = V_D - V_S \doteq \text{Drain-to-Source Voltage}$$

Now guess what happens—**current** begins to flow through the **induced channel**!

**Q:** Current! I thought current could **not** flow because of the two p-n junctions in the NMOS device!



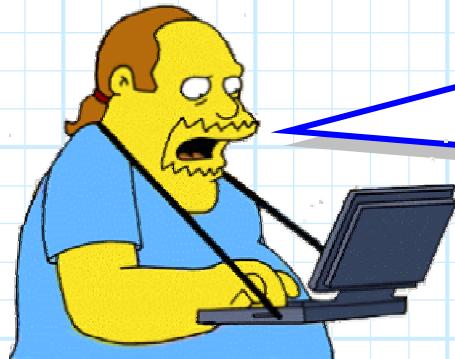
**A:** Remember, that was **before** we applied a sufficient **gate voltage**. With this voltage applied, an **n**-type channel is induced, forming a **conducting channel** from drain to source!

Recall that because of the  $\text{SiO}_2$  layer, the gate current is **zero** (i.e.,  $i_G = 0$ ).

Thus, all current **entering the drain** will **exit the source**. We therefore conclude that:

$$i_S = i_D$$

As a result, we refer to the channel current for NMOS devices as simply the **drain current**  $i_D$ .



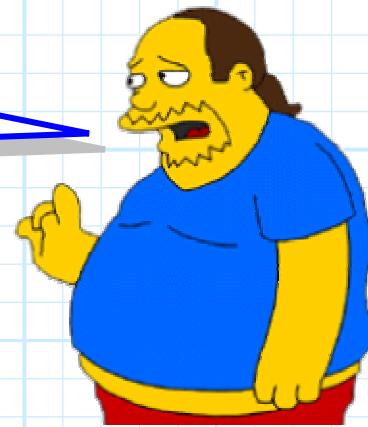
**Q:** So, I see that you have now defined current  $i_D$  and voltages  $v_{GS}$  and  $v_{DS}$ . Just how are these parameters related?

**A:** First, we find that an increasing  $v_{GS}$  or, more specifically, an increasing **excess gate voltage**  $v_{GS} - V_t$  will result in a **higher channel conductivity** (in other words, a lower channel resistivity).

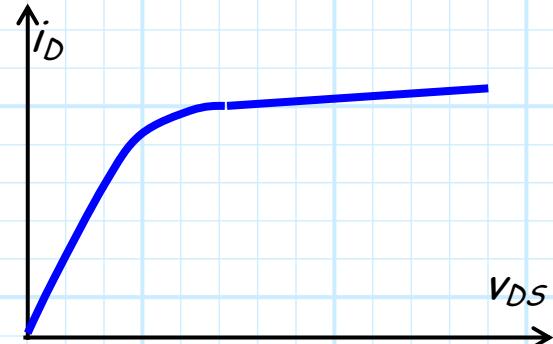
Thus, we find that the **drain current**  $i_D$  will **increase** as a positive **excess gate voltage**  $v_{GS} - V_t$  increases (assuming that  $v_{DS} > 0$ ).

This process, of increasing the induced channel conductivity by increasing the excess gate voltage, is otherwise known as **channel enhancement**. This is where the **enhancement MOSFET** gets its name!

**Q:** OK, but what about the relationship between drain current  $i_D$  and voltage  $v_{DS}$ ?



**A:** This relationship is a little complicated! Generally speaking, however, a **positive**  $v_{DS}$  results in a **positive**  $i_D$ , and the **larger** the  $v_{DS}$ , the **larger** the drain current  $i_D$ .



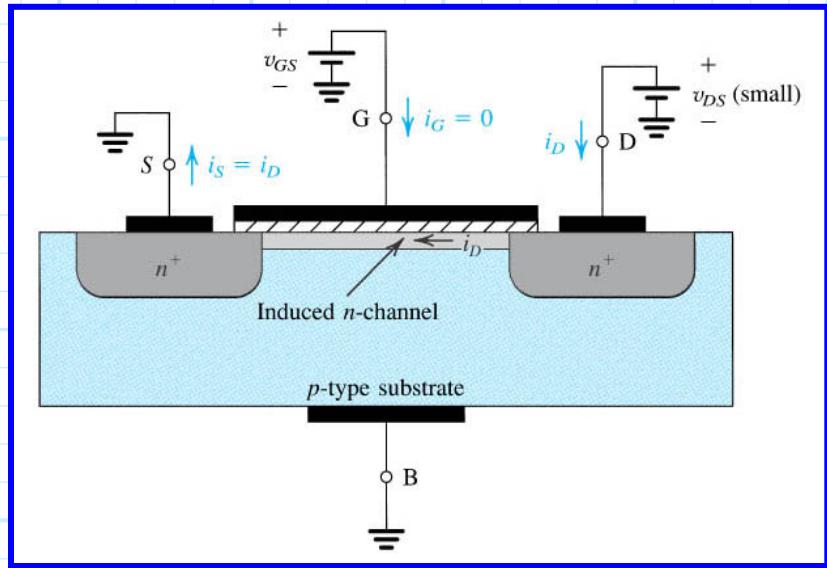
More specifically, we find that when  $v_{DS}$  is **small** (we'll see how small later), the drain current will be **directly proportional** to the voltage drain to source  $v_{DS}$ .

$$i_D \propto v_{DS} \quad \text{if } v_{DS} \text{ small}$$

In other words, if  $v_{DS}$  is **zero**, the drain current  $i_D$  is **zero**. Or, if the voltage  $v_{DS}$  **increases** by 10%, the drain current will likewise **increase** by 10%. Note this is just like a **resistor**!

$$i = \frac{V}{R} \quad \therefore i \propto V$$

Thus, if (and **only if!**)  $v_{DS}$  is small, the induced channel behaves **like a resistor**—the current through the channel ( $i_D$ ) is **directly proportional** to the voltage across it ( $v_{DS}$ ).

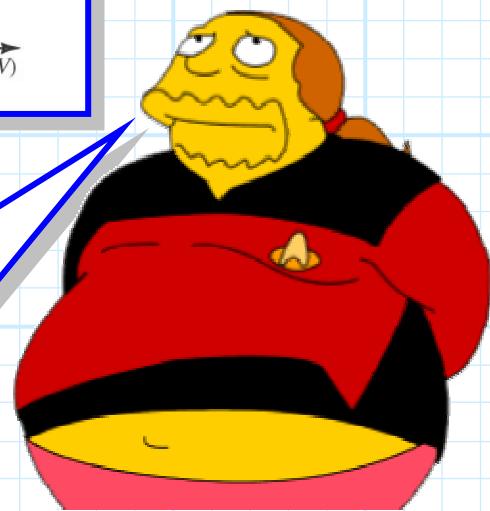
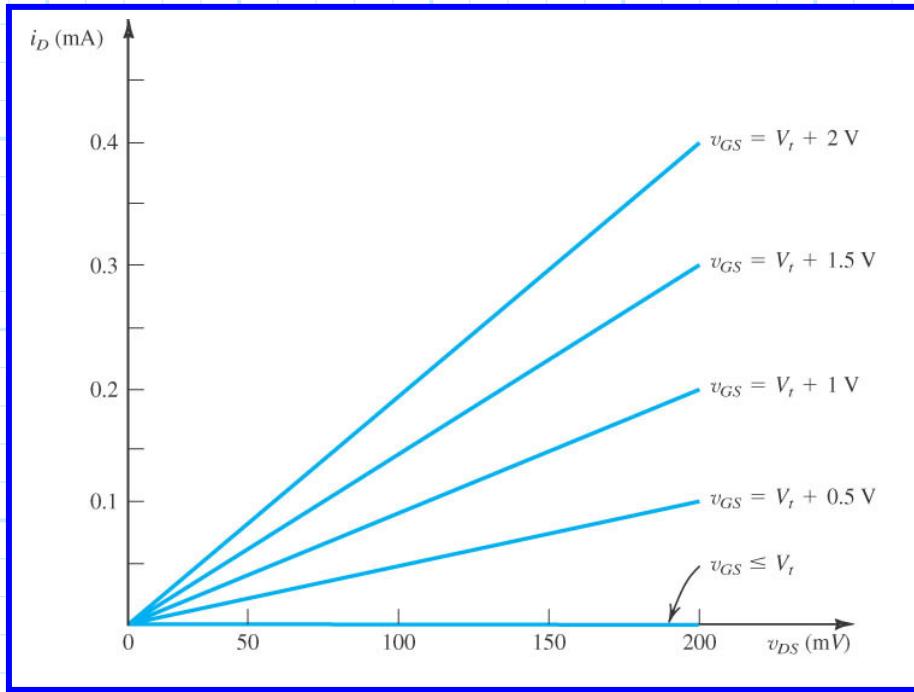


In other words, we can (for small values of  $v_{DS}$ ), define a **channel resistance**  $r_{DS}$ :

$$\text{Since } i_D \propto v_{DS}, \quad \frac{v_{DS}}{i_D} \doteq r_{DS} \quad (\text{if } v_{DS} \text{ small})$$

Note that this resistance value depends on the **conductivity** of the induced channel—which in turn is dependent on the **excess gate voltage**!

Thus, if we were to plot drain current  $i_D$  versus  $v_{DS}$  for various excess gate voltages, we would see something like this:



**Q:** Yawn! It is apparent that an NMOS transistor is so simple that virtually any intergalactic traveler should be able to understand it. It's just a voltage controlled resistor—right?

**A:** **WRONG!** Remember, channel resistance  $r_{DS}$  only has meaning if  $v_{DS}$  is small—and most often  $v_{DS}$  will not be small!

As  $v_{DS}$  increases from our presumably small value, we find that strange things start to happen in our channel!

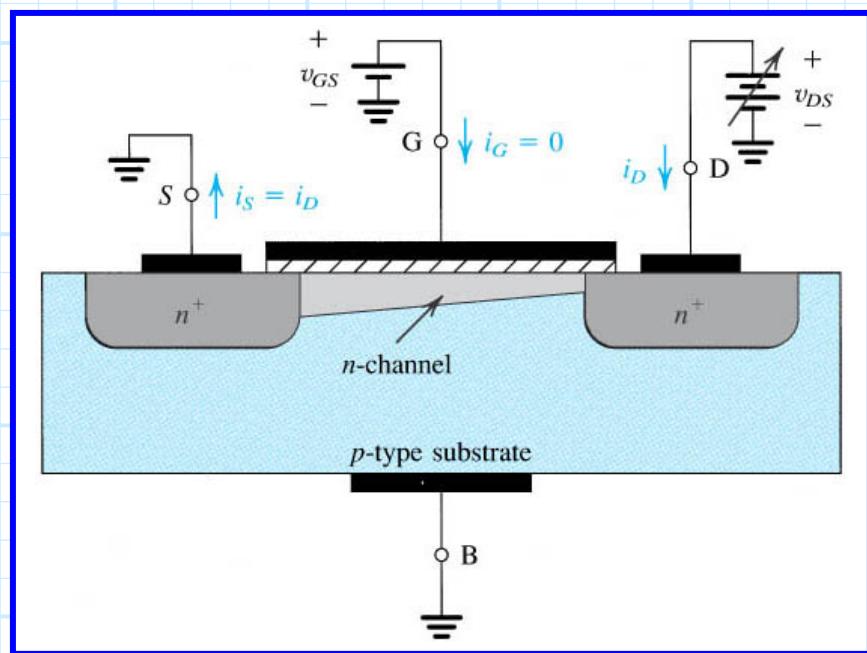
Recall that primarily, the free-electrons in our inversion layer (the induced channel) were attracted to the gate from the heavily doped n+ Silicon regions under the drain and source.

But the **gate** now has **competition** in attracting these free electrons!

It was "easy" to attract free electrons to the gate when the **gate electrode voltage** was much **larger** than both the drain and source voltage (i.e., when  $v_{GS} \gg v_{DS}$ ). But as the **drain** voltage increases, it begins to attract **free electrons** of its own!

Recall that **positive current entering** the drain will actually consist mainly of **free electrons exiting** the drain! As a result, the **concentration of free-electrons** in our inversion layer will begin to **decrease** in the vicinity of the drain.

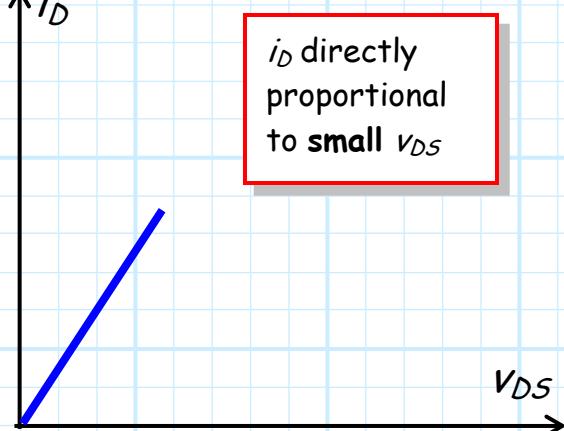
In other words, **increasing  $v_{DS}$**  will result in **decreasing channel conductivity**!



Thus, increasing the  $v_{DS}$  will have **two effects** on the NMOS device:

1. Increasing  $v_{DS}$  will **increase the potential difference** (voltage) across the conducting channel, an effect that works to **increase** the drain current  $i_D$
2. Increasing  $v_{DS}$  will **decrease the conductivity** of the induced channel, and effect that works to **decrease** the drain current  $i_D$ .

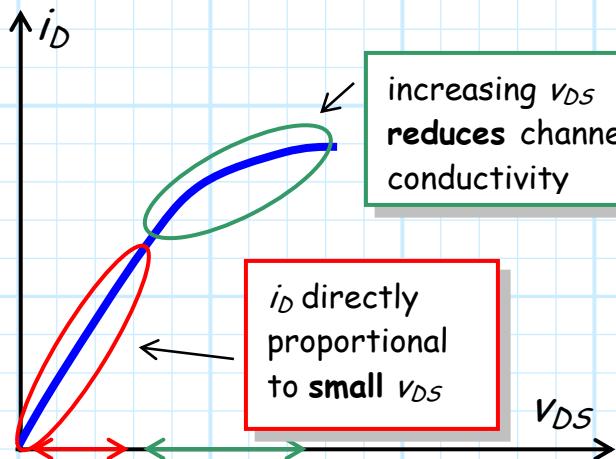
For **small** values of  $v_{DS}$ , the second effect is **tiny**, so that the increase in drain current is **directly proportional** to the increase in voltage  $v_{DS}$  (hence, we can define channel **resistance**  $r_{DS}$ ). For example, a **10% increase** in  $v_{DS}$  will result in a **10% increase** in drain current.



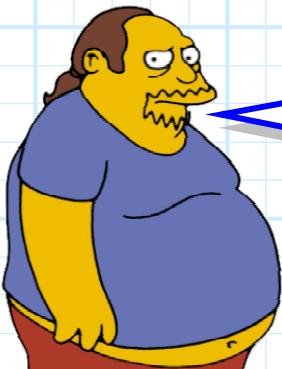
However, as  $v_{DS}$  increases, the **second effect** will become more and **more pronounced**. We find then that the drain current will no longer be directly proportional to the voltage  $v_{DS}$ . The reduction in channel conductivity will begin to "counteract" the increase in potential across the channel.

For example, a **10% increase** in  $v_{DS}$  may result in only a **9% increase** in  $i_D$ . Likewise, if we increase  $v_{DS}$  another 10%, the drain current may then increase **only 8%** (and so on).

Eventually, we find that the an increase in  $v_{DS}$  will result in no further increase drain current  $i_D$ !! Effect 2 will **completely** "counteract" effect 1, so that there is **no more** increase in drain current as  $v_{DS}$  increases.

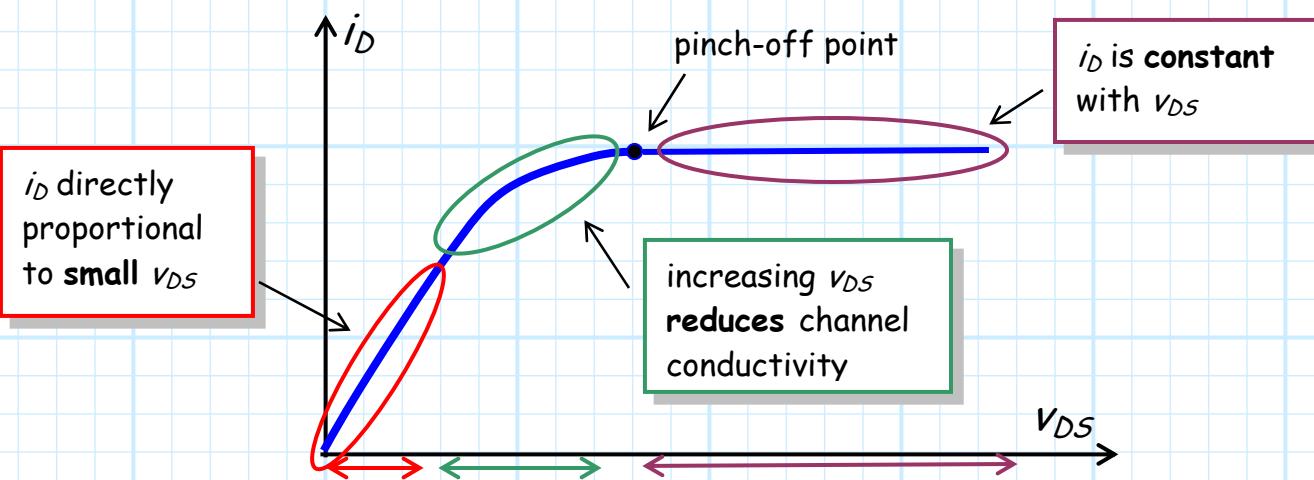


When this occurs, we say that we have "**pinched-off**" the induced channel—in other words the channel is in pinch off.



**Q:** So, if we **continue** to increase  $v_{DS}$  after the channel is "**pinched off**", does the drain current actually begin to **decrease**?

**A:** NO! An interesting thing happens when the channel is in pinch off. As we further increase  $v_{DS}$ , the drain current  $i_D$  will remain **unchanged** (approximately)! That is, the drain current will be a **constant** (approximately) with respect to  $v_{DS}$ .



Note that there are **three distinct channel conditions** in for NMOS operation.

- \* Depending on the value of  $V_{GS}$ , we can have an **induced channel**, or **no conducting channel at all!**
- \* Then if we have an **induced channel** (i.e.,  $V_{GS} - V_t > 0$ ), (depending on the value of  $V_{DS}$ ) the channel can be either **be pinched-off or not!**

Each of these **three** possibilities has a **name**—they are the names of our **NMOS transistor modes**!

1. **Cutoff** - When  $V_{GS} - V_t < 0$ , **no** channel is induced (no inversion layer is created), and so  $i_D=0$ . We call this mode **CUTOFF**.
2. **Triode** - When an induced channel is present (i.e.,  $V_{GS} - V_t > 0$ ), but the value of  $V_{DS}$  is **not** large enough to pinch-off this channel, the NMOS is said to be in **TRIODE** mode.
3. **Saturation** - When an induced channel is present (i.e.,  $V_{GS} - V_t > 0$ ), and the value of  $V_{DS}$  is **large** enough to pinch-off this channel, the NMOS is said to be in **SATURATION** mode.

We can summarize these modes in a table:

MODE	INDUCED CHANNEL?	CHANNEL PINCH-OFF?
CUTOFF	NO	N/A
TRIODE	YES	NO
SATURATION	YES	YES

